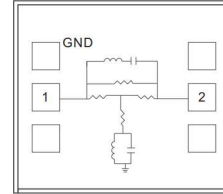


Performance

- Frequency: 1-2GHz
- Insertion Loss: $\leq 0.9\text{dB}$
- Attenuation: 3dB
- Impedance: 50Ω
- Chip size: $0.82 \times 1.3 \times 0.1\text{ mm}$

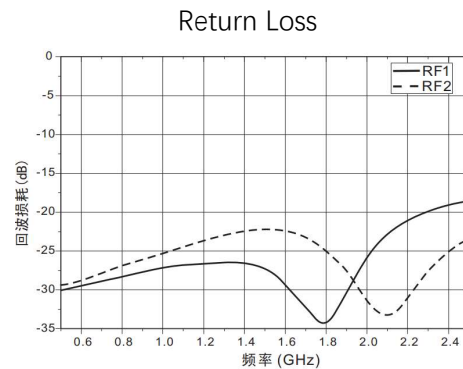
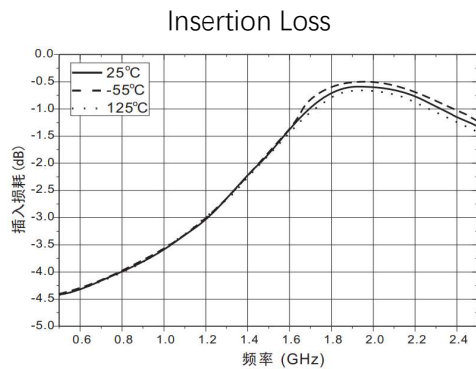
Function Diagram



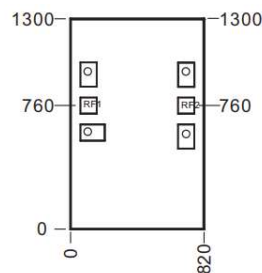
Electrical Specifications (TA=+25°C, 50Ω system)

Parameter	Min	Typical	Max	Unit
Frequency Range		1.0-2.0		GHz
Insertion Loss	-	0.7	0.9	dB
Attenuation	-	3.0	-	dB
Input Return Loss	21	24	-	dB
Output Return Loss	25	27	-	dB

Test Curves (Die chip test)



Outline Size



Note:

1. Unit: μm
2. Bottom side is gold plated
3. Bottom side is GND
4. Bonding pads is gold plated
Pads size: $100 \times 100\ \mu\text{m}$
5. Don't bonding on thru holes
6. Tolerance: $\pm 50\ \mu\text{m}$

Assembly Drawing



Bonding Pads Definition

Number	Symbol	Description
RF1、RF2	RF Ports	RF ports, 50 ohm impedance
	GND	Bottom side of chip must be grounded

Absolute Max. Ratings

Static Protection Grade	Class 1A
Input Power	30 dBm
Storage Temperature	-65~150°C
Operating Temperature	-55~125°C